



An ISO/TS 16949:2002 and ISO 9001:2000
Registered Company

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Request for Quote

IC Interconnect offers a wide range of services to meet customer needs. In order that ICI might provide the most comprehensive response please fill out this RFQ with as much information as possible. ICI's engineering staff will assess your requirements and evaluate them against our technology offerings in terms of process parameters and design rules. The sales staff will then be in a position to provide a budgetary quote for you to work with. In the event that this level of detail is premature, please feel free to contact us by phone or e-mail to discuss your application.

Contact Name:
Company Name:
Company Address:

Phone:
Fax:
Email:

Device Name:

Services Requested: (select)

1. Ni/Au UBM + Solder Bumping (Flip Chip) (please fill out sections A through D)
2. Ni/Au UBM + Ball Placement (WLCSP) (please fill out sections A through D)
3. Ni/Au as a wire bond surface (please fill out sections A through C)
4. Ni/Au as a hard mini bump (please fill out sections A through C)
5. Solder Deposition on your UBM (please fill out sections A, B and D)
6. Reliability Modeling (submit, you will be contacted for details)
7. Laser Mark (please fill out sections A, B and E)
8. Flip Chip Assembly (submit, you will be contacted for details)

Passivation

Thickness micron

Backside Condition (select)Oxide
Si
Polymer
Ag
Au
Other**C. Ni/Au Plating Related Information****Pad Metal Composition (select)**Aluminum %Al %Si %Cu
Copper
Other**Pad Metal Thickness** t= micron, ± micron**Passivation Opening Size and Shape (select)**Round dia= micron
Rectangle x= micron, y= micron
Other**Open Metal (other than pads to be bumped)**in the Streets yes no
in the Die yes no
open Fuses yes no**Wafer contains Ink Dots** yes no**Desired Ni Thickness** t= micron**Minimum Spacing between open Metal (edge to edge)** micron**D. Solder Related Information****Bond Pad Layout: (select)**Full Area Array
Peripheral (1 row)
Peripheral (2 rows)
Other**Solder Alloy**63Sn/37Pb
90Pb/10Sn
95.5Sn/3.8Ag/0.7Cu
Other**Minimum Pitch within a Die (centerline to centerline)** micron**Minimum Pitch Die to Die (centerline to centerline)** micron

